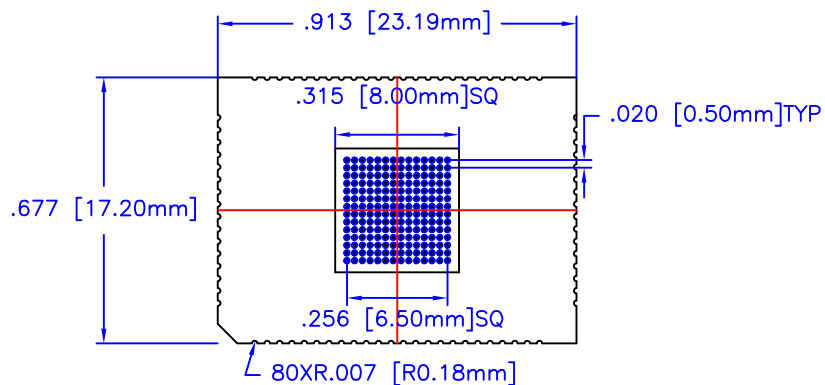


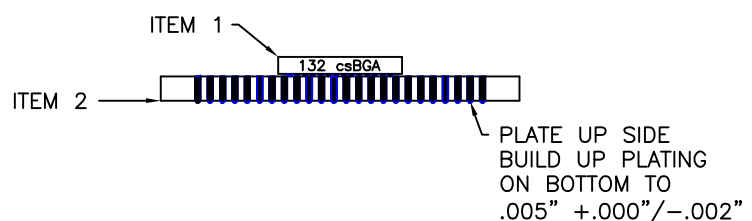
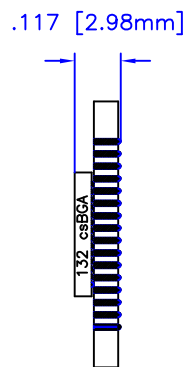
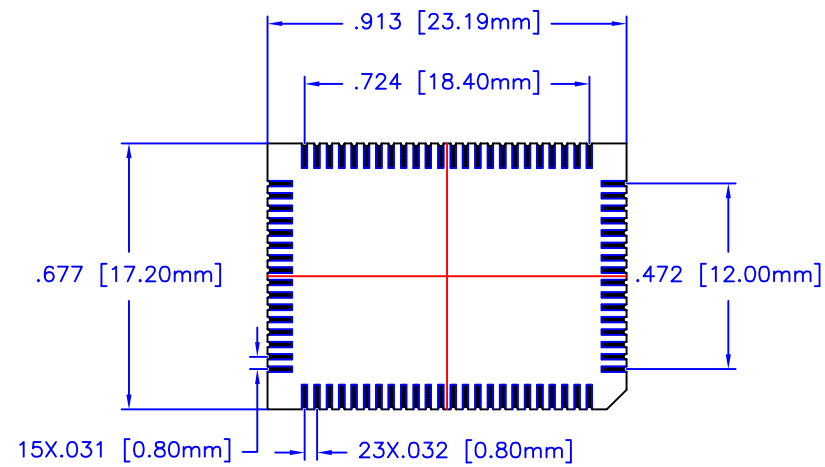
MATERIAL SPECIFICATIONS:
 STANDARD MATERIAL:
 GLASS EPOXY FR-4, IPC-4101/24,
 MIL-S-13949/04-GF/GFGUL:
 94V-0, CONTINUOUS USE TEMP 150C,
 HEAT DEFLECTION TEMP(264 PSI)175C

REVISIONS				
ZONE	REV	DESCRIPTION	DATE	APPROVED
---	A	RELEASED	12/07/05	

TOP VIEW




BOTTOM VIEW



NOTES:
 ITEM 1 SOLDERS TO TOP
 SIDE OF ITEM 2 (PCB)

B.O.M.	PART NUMBER	QTY
1)	132csBGA	1
2)	132csBGA80QF	48

CONTRACT NO.		 ADAPTERS-PLUS WWW.ADAPT-PLUS.COM, PH 209-839-0200			
APPROVALS:		CHIP CONVERTER FOR 132 csBGA TO 80 PQFP			
DRAWN BY: ANDREW MONTOYA					
CHECKED: MIKE OIDEM		SIZE A	FSCM NO.	DWG NO. CA132csBGA-80PQFP-LS	REV A
ISSUED: ANDREW MONTOYA		SCALE: 4:1	DATE : 12/07/05	SHEET: 1 OF 1	